

ABSTRACT OF THE DISCLOSURE

An LOC type semiconductor package has a lead frame with leads divided into general leads and stable leads. The ends of the general leads are at the periphery of the

5 semiconductor chip and separated from the semiconductor chip, such that the general leads do not come into contact with the semiconductor chip. The ends of the stable leads attach to a central portion of the surface of the semiconductor chip. Accordingly, since all the inner leads are not collectively arranged on the surface of the semiconductor chip but only the
10 stable inner leads are located thereon, semiconductor chips in a variety of sizes can be mounted on the lead frame. Thus, there is no need for a new lead frame design whenever the semiconductor chip size is changed and a single lead frame design can be mass produced for use in several different products.

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